

PE5101D

Rugged High Performance Edge Computer Supports Intel® 13th/12th Core™ CPU, 2.5" Hot-Swappable HDD Tray, RAID 0/1 and up to 200W Graphics Card



Features

- Supports Intel® 13th/12th Core™ CPU with R680E chipset
- Supports dual 2.5" hot-swappable HDD tray & RAID 0/1
- Rich I/O with 3 x 2.5 GbE, 10 x USB, 6 x COM
- PCIe x16 & PCIe x4 expansion slots support up to 200-watt Graphics card
- 8 to 48V wide-range DC-in w/ built-in ignition power control
- Wide operating temperature range: -25° C to 60° C

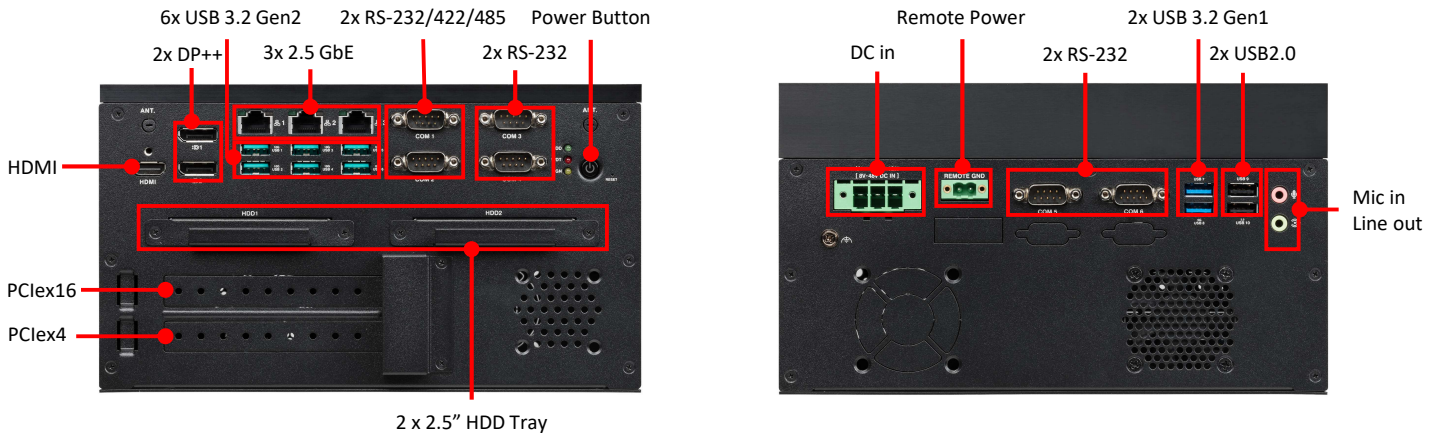
Specifications

System	CPU	Intel® Core™ i9-13900TE	Intel® Core™ i7-13700TE	Intel® Core™ i5-13500TE	Intel® Core™ i3-13100TE
	TDP	35W	35W	35W	35W
	# of Cores	24	16	14	8
	Base Freq.	1.0GHz	1.1GHz	1.3GHz	2.4GHz
	Max Turbo Freq.	5.0GHz	4.8GHz	4.5GHz	4.1GHz
	Chipset	Intel® R680E			
	Memory	2 x SO-DIMM (supports DDR5 ECC/non-ECC, up to 4800 MHz, max. 64GB)			
I/O Interfaces	Display	1 x HDMI, supports up to 4096 x 2160 @ 30 Hz 2 x DP++, supports up to 4096 x 2160 @ 60 Hz			
	Ethernet	3 x 2.5 GbE, RJ45 (Intel® i226-IT)			
	AMT	Supports Intel® vPro/ AMT			
	USB	6 x USB 3.2 Gen 2 (10Gbps) 2 x USB 3.2 Gen 1 (5Gbps) 2 x USB 2.0			
	COM	2 x RS-232/422/485 4 x RS-232			
	Audio	1 x Mic-in 1 x Line-out			
	DIO	8-bit isolated DIO(4-in/4-out, terminal block, optional)			
Storage	2.5" SATA	2 x 2.5" (supports hot-swappable HDD tray, RAID 0/1)			
	M.2 M Key	1 x M.2 2280 M-key (PCIe Gen4x4)			
Expansion Slot	M.2 E Key	1 x M.2 2230 E-key (PCIex1/USB2.0)			
	M.2 B Key	1 x M.2 3042/3052 B-key with dual nano-SIM slot (PCIex1/USB 3.2 Gen1/USB2.0)			
	Mini PCIe	1 x Mini PCIe socket (PCIex1/USB 2.0)			
	PCIe Slot	1 x PCIe Gen4 x4 slot 1 x PCIe Gen4 x16 slot, the max in size 229 x 123.24 x 49.6 mm ¹			
Power	Power input	8 to 48 V DC-in, 3-pin terminal block (V+, GND, IGN)			
	Remote switch	2-pin terminal block (Remote, GND)			
Mechanical	Mounting	Wall-mount			
	Dimensions	242 x 241.4 x 137mm			
	Weight	5.81 kg			
Environment	Operating Temp.	-25° C to 60° C ²			
	Storage Temp.	-40° C to 85° C			
	Relative Humidity	10 to 95% (non-condensing)			
	EMC	CE, FCC, BSMI			
	Safety	CE-LVD, CB, BSMI, CCC			
	Vibration	Operating: MIL-STD 810H Method 514.8, Category 4 & 3Grms, 5-500 Hz, 3 Axes			
	Shock	Operating: MIL-STD 810H Method 516.8, Procedure I, Table 516.6-II; 20 G 11ms			
Green	GA (RoHS)				
Security	TPM	Supports dTPM v2.0			
Others	Watch dog timer	Supported			
	OS	Windows® 10 IoT Enterprise (64-bit) / Linux by Project support			

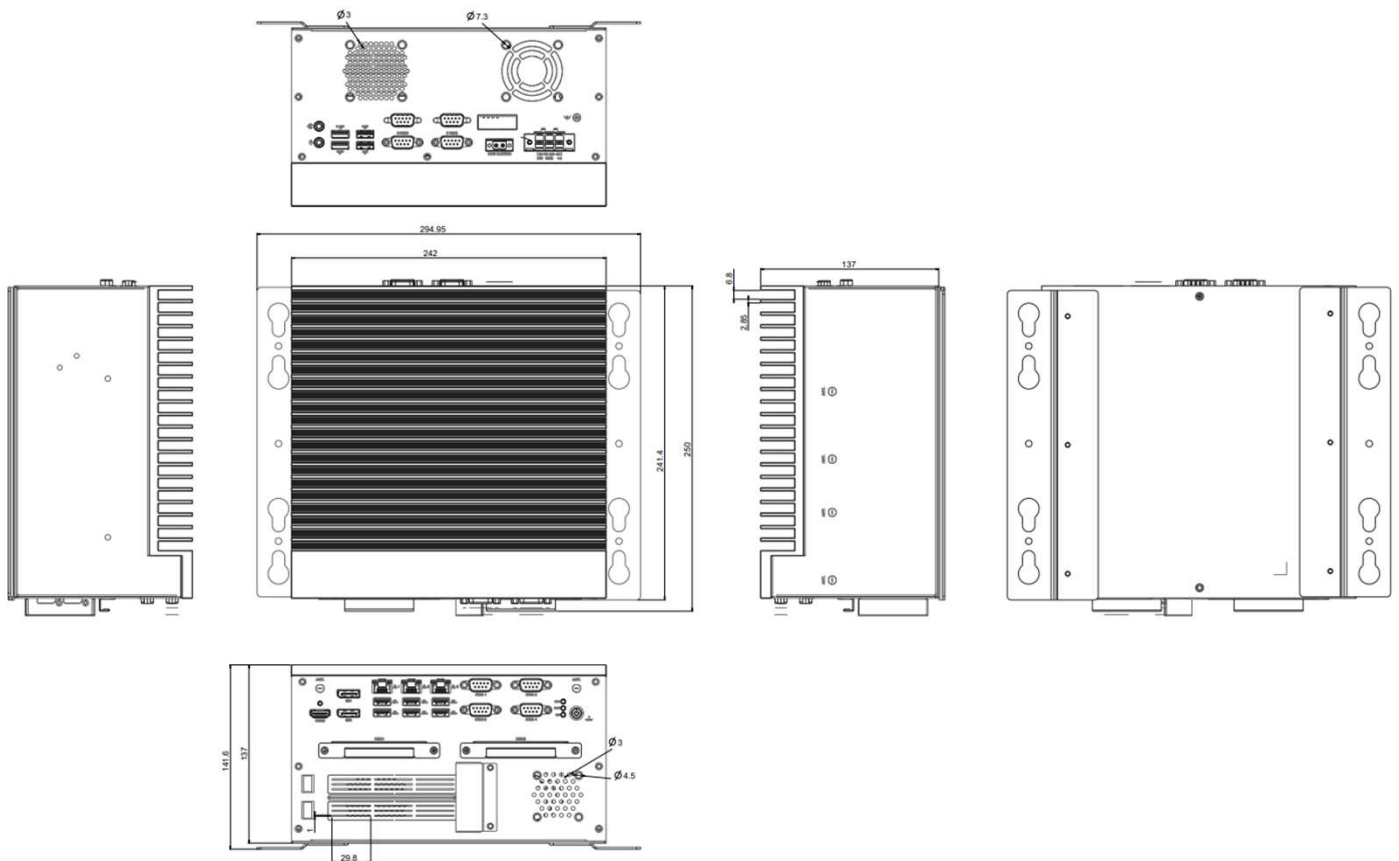
1. If the length of add-on card is over 200 mm, the location of system fan needs to be adjusted, please refer to UMN for more detail.

2. For wide temperature demand, the industrial memory & storage are required.

Appearance:



Dimension (mm):



Ordering Information:

CPU	Chipset	SO-DIMM	LAN	2.5" SATA	COM	DIO	OP Temperature
i9-13900TE	R680E	2	3	2	6	Optional	-25~60°C/0~40°C
i7-13700TE	R680E	2	3	2	6	Optional	-25~60°C/0~40°C
i5-13500TE	R680E	2	3	2	6	Optional	-25~60°C/0~40°C
i3-13100TE	R680E	2	3	2	6	Optional	-25~60°C/0~40°C

* Please check with your importer or integrator for system level certification.

Packing List:

Item	Qty
Power terminal block, 3-PIN	1
Remote power terminal block, 2-PIN	1
GPU Power cable	1
Wall mount kit	2
Wall mount screw pack	1
Anti shock & vibration damper	8
SSD screw pack	2
PCIe card screw pack	2

Optional Accessories:

Item	Description
ADAPTER	
	Power adapter, 330W 24V, input voltage 100 to 264VAC, output voltage 24VDC with 13.75A DC load, 0 to 40°C operating temperature
POWER CORD	
	Power cord with United States (US) plug
	Power cord with Europe (EU) plug
	Power cord with China (CN) plug
	Power cord with Australia (AU) plug
	Power cord with United Kingdom (UK) plug
	Power cord with Korea (KR) plug
	Power cord with Taiwan (TW) plug